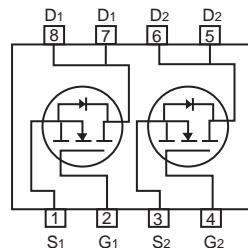
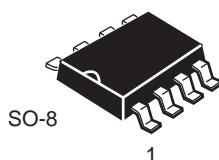


## Dual N-Channel Enhancement Mode Field Effect Transistor

## FEATURES

- 30V, 9A,  $R_{DS(ON)} = 16\text{m}\Omega$  @  $V_{GS} = 10\text{V}$ .  
 $R_{DS(ON)} = 23\text{m}\Omega$  @  $V_{GS} = 4.5\text{V}$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.

5

ABSOLUTE MAXIMUM RATINGS  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	9	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	36	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

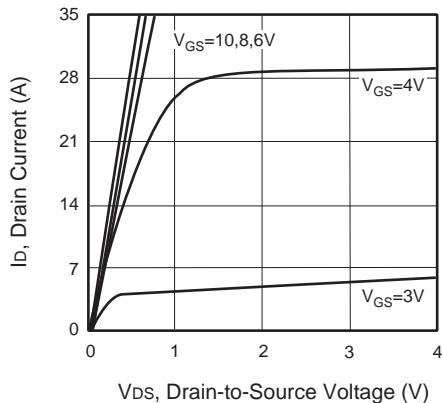
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$		13	16	$\text{m}\Omega$
On-Resistance		$V_{\text{GS}} = 4.5\text{V}, I_D = 7.2\text{A}$		18	23	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		950		pF
Output Capacitance	$C_{\text{oss}}$			165		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			85		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 0.3\Omega$		12	24	ns
Turn-On Rise Time	$t_r$			3.5	7	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			32	64	ns
Turn-Off Fall Time	$t_f$			6.7	13.4	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}$		14.8	19.7	nC
Gate-Source Charge	$Q_{\text{gs}}$			2.9		nC
Gate-Drain Charge	$Q_{\text{gd}}$			1.8		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$			9		A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 9\text{A}$		1.3		V

**Notes :**

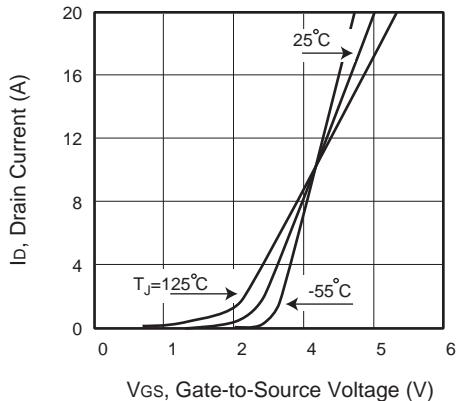
a.Repetitive Rating : Pulse width limited by maximum junction temperature.

b.Surface Mounted on FR4 Board,  $t \leq 10$  sec.c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

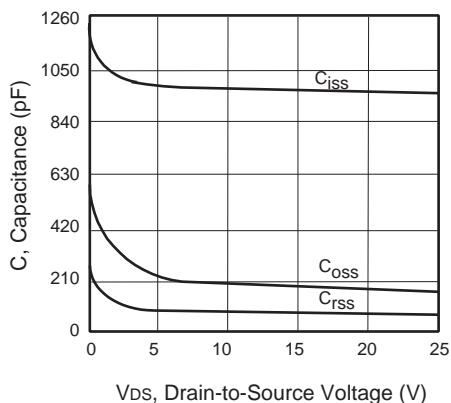
d.Guaranteed by design, not subject to production testing.



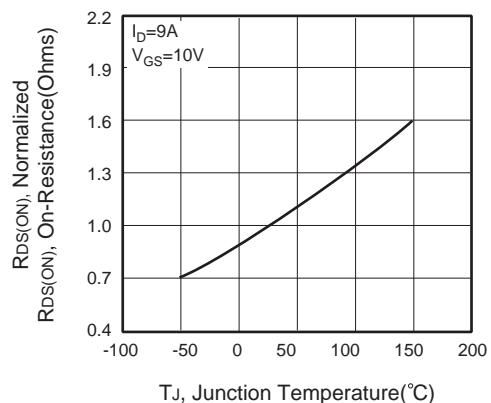
**Figure 1. Output Characteristics**



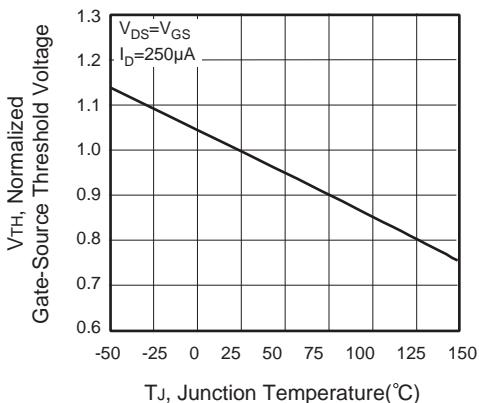
**Figure 2. Transfer Characteristics**



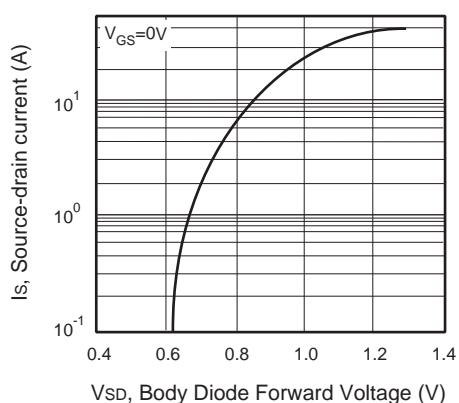
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

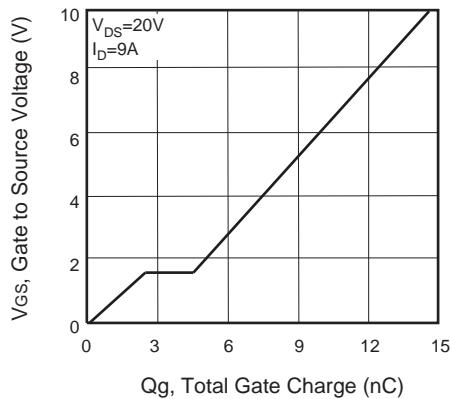


Figure 7. Gate Charge

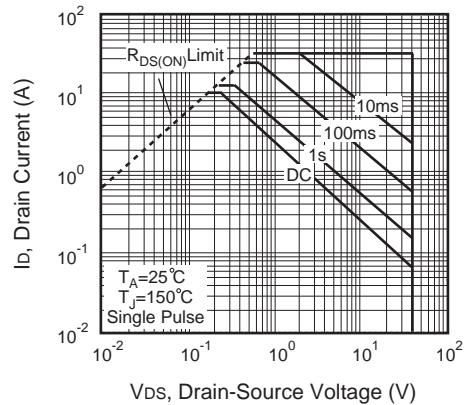


Figure 8. Maximum Safe Operating Area

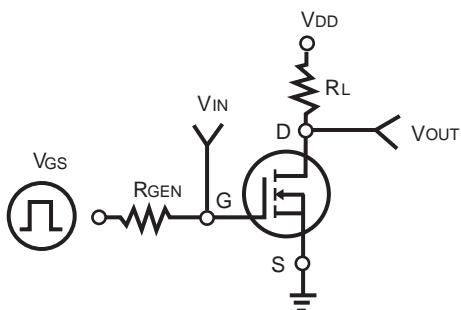


Figure 9. Switching Test Circuit

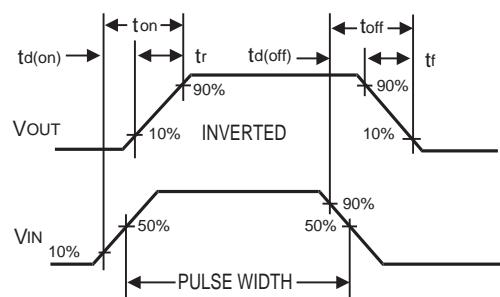


Figure 10. Switching Waveforms

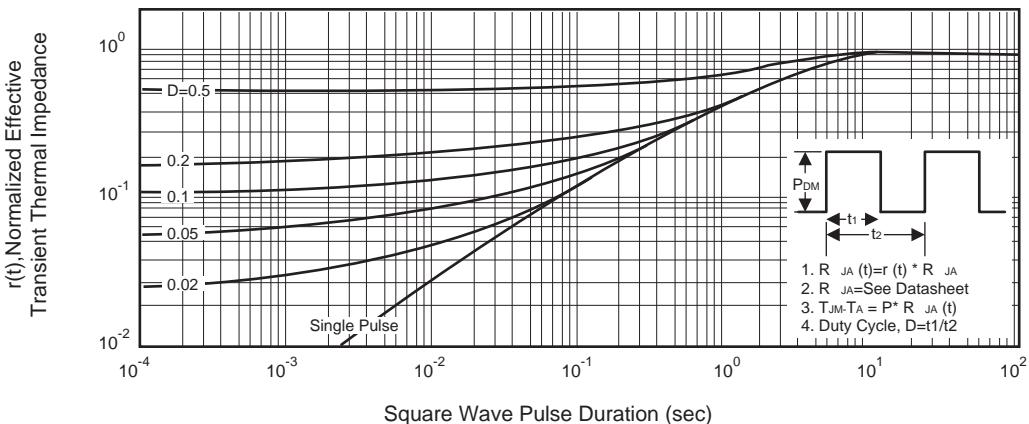


Figure 11. Normalized Thermal Transient Impedance Curve